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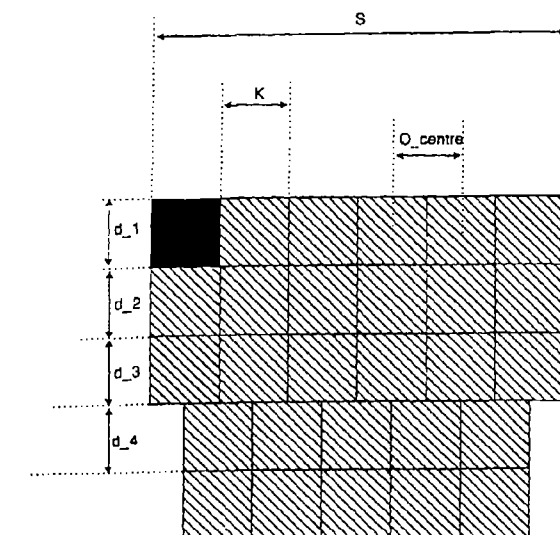
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(54) Title: CONTROL OF LASER MACHINING



A five step machining strategy requiring a total of 28 laser scans.



162162

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(57) Abstract: A UV laser beam is used to machine semiconductor. The beam intensity (I_b) is chosen so that it lies in a range of such values for which there is an increasing (preferably linear) material removal rate for increasing I_b . An elongate formation such as a trough or a slot is machined in n scans laterally offset (O_{centre}), for each value of z -integer in the z direction.



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